Photon-to-Digital Converters – A 3D Integrated Digital Single-Photon Detector for Large Scale Photodetection Systems and more...

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- ² TRIUMF, Vancouver, Canada

TRIUMF Science Week, July 2025









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nEXO Collaboration

nEXO Canada

ARGO Collaboration



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National Laboratory



Fonds de recherche sur la nature et les technologies



















- Scintillating crystal-based systems
 - Positron Emission Tomography
 - Computed Tomography
 - Neutron Imaging

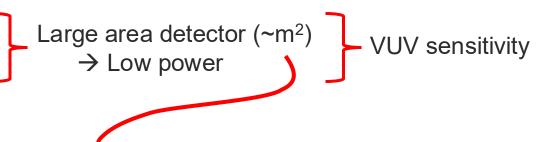
Precise single-photon timing resolution

Visible spectrum

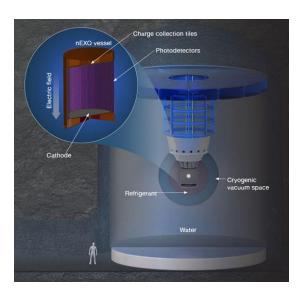


Mid-sized Animal LabPET II

- Noble liquid experiments (Argon and Xenon)
 - Dark matter search
 - Neutrino physics



5 to 100s m² of detector area!

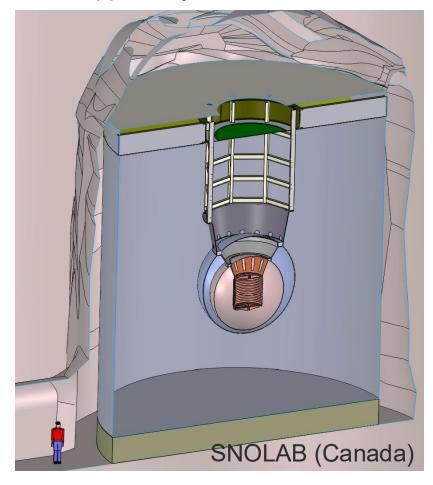


The nEXO time projection chamber (top left inset) allows measurement of energy and location of double beta decays.

https://nexo.llnl.gov

nEXO – neutrino search

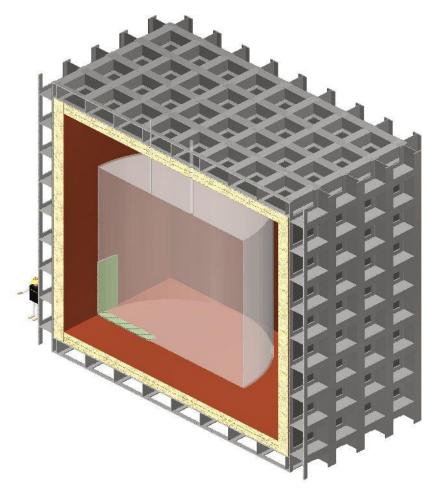
¹³⁶Xe 0νββ decay – xenon as scintillator



5 tonnes of LXe -4.5 m^2 of photon detectors

ARGO – dark matter search

LAr as interaction media and scintillator

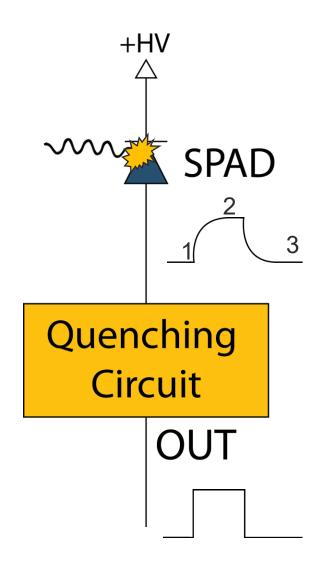


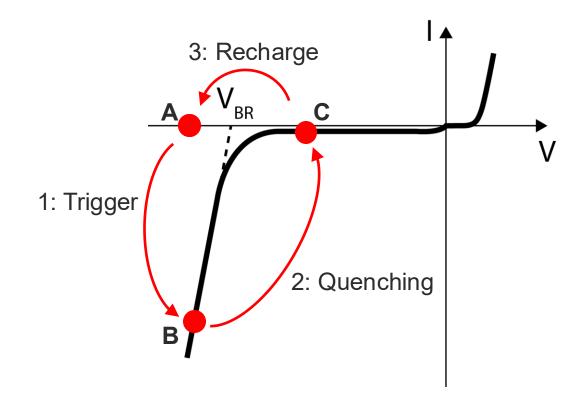
300 tonnes of LAr - 250 m² of photon detectors



The Photon-to-Digital Converter Concept

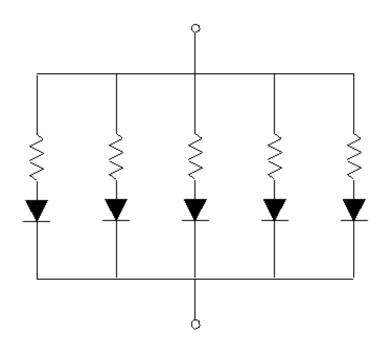
How to turn a single photon into a digital pulse

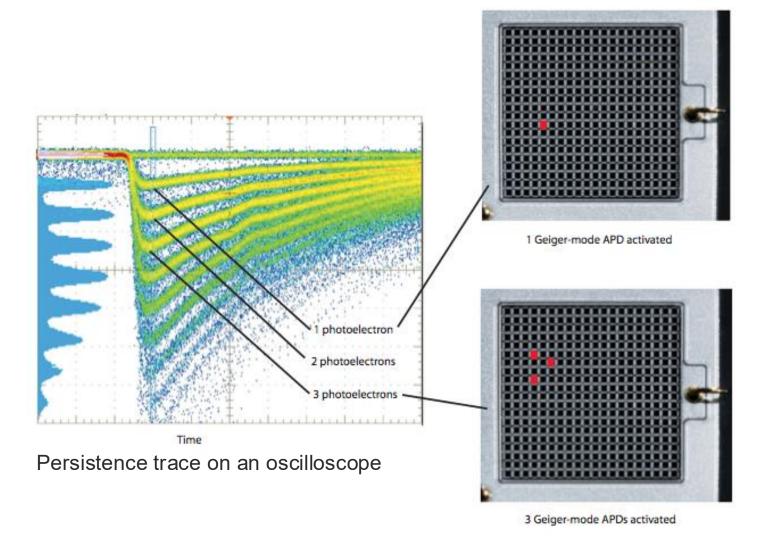




- 1. Time precision
- 2. Sensitivity gain >10⁵ single photon
- 3. Low cost

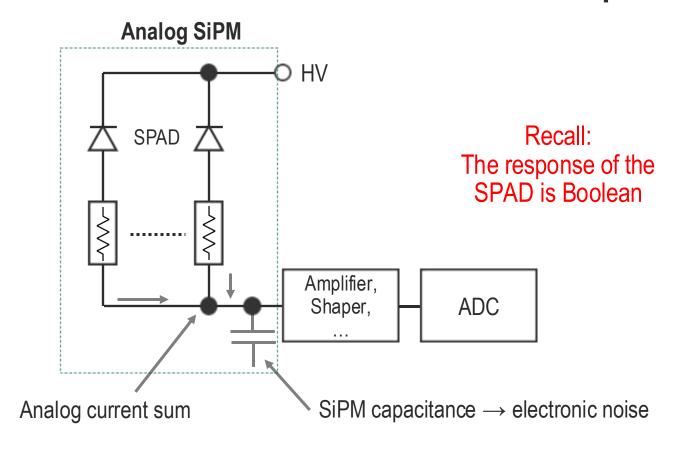
Array of SPADs in parallel quenched passively

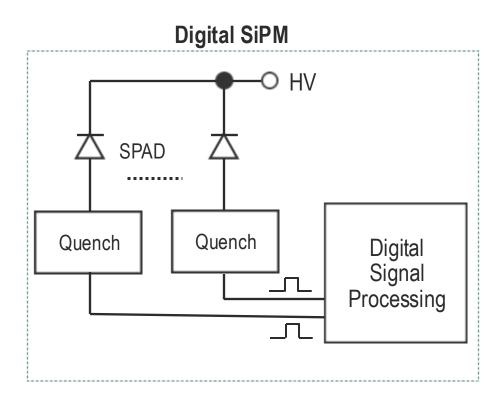




Source: Hamamatsu

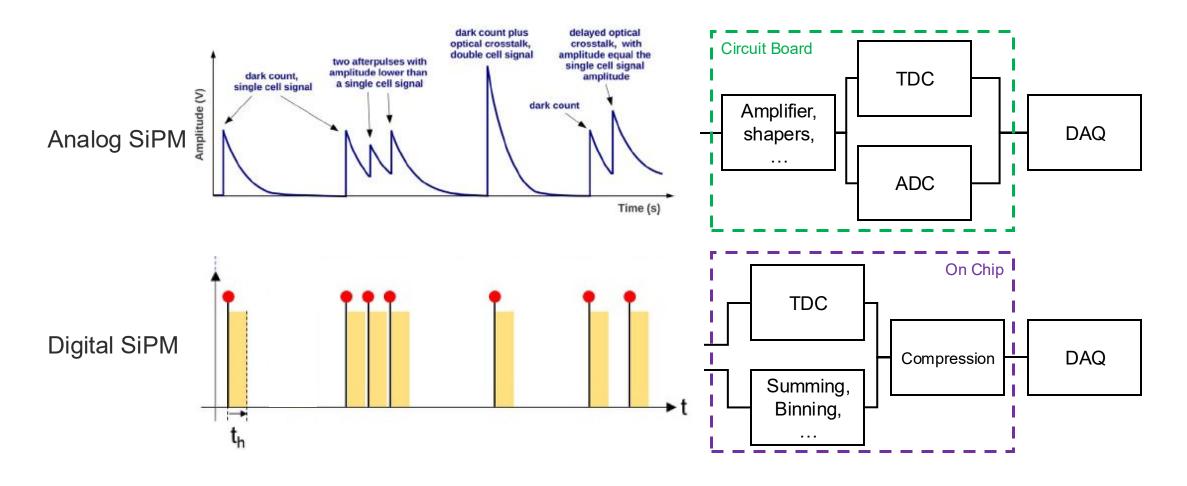
SiPM – Silicon Photo Multiplier: an array of SPADs





The amplifier transforms charge into voltage and then BACK to digital.

Individual SPAD readout, no D/A+A/D conversion. Everything stays digital.



Are the individual photon pulse shapes really needed?

(with all their complications to analyse)

11

Panel discussion on Wednesday 11h30

Science Technology:

When will digital SiPM move beyond the R&D phase for subatomic physics and other applications?



Nicolas D'Ascenzo Huazhong University of Science and Technology China



Peter Fischer
Heidelberg University
Germany



Fabrice Retiere
TRIUMF/Simon Fraser U.
Canada

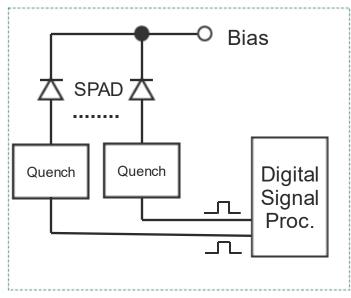


Serge Charlebois Université de Sherbrooke Canada

Questions and opinions and welcome!!!

Digitally readout array of Single Photon Avalanche Diode (SPAD)

Photon-to-Digital Converter

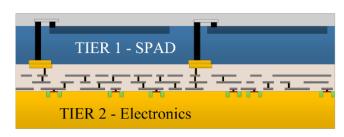


- Direct digital conversion:
 - Single photon resolution on the whole dynamic range
 - Can lower power significantly consumption
- Disabling noisy SPADs: reducing noise
- Programmable hold-off delay: mitigation of afterpulsing
- Embedded signal processing: sum, dark count filters, time-to-digital conversion, etc.

Pratte JF et al. "3D Photon-to-Digital Converter for Radiation Instrumentation: Motivation and Future Works" (2021) Sensors;21(2):598. doi: 10.3390/s21020598

SPAD array and CMOS readout vertically stacked (3D) to form a single detector chip





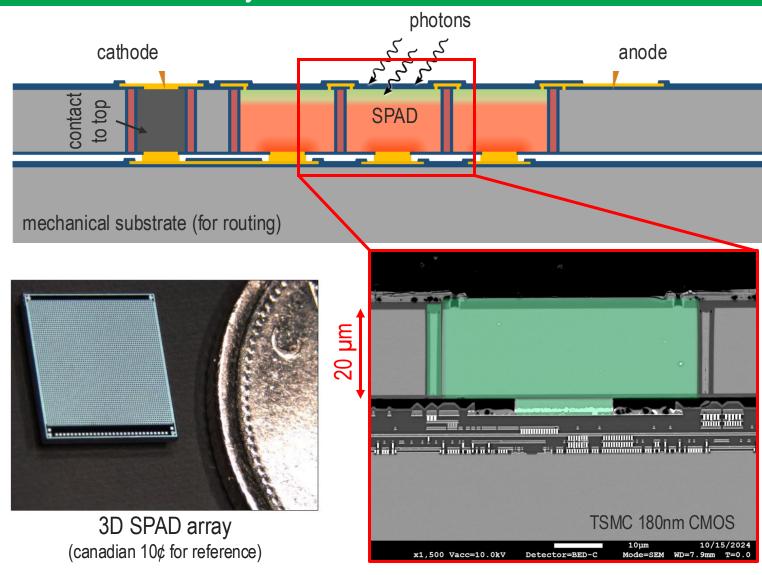


Development of the SPAD array layer and low power PDC

1st fabrication run completed (Octobre 2024)

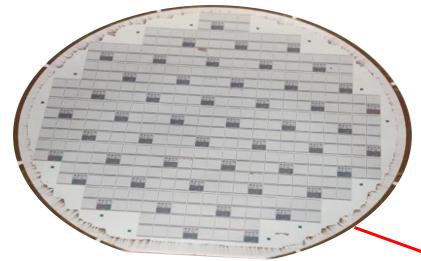
Thin SPAD layer + CMOS readout

- p+n SPAD [1]
- 64 × 64 SPAD Array
- 78 µm pitch
- Al-Ge eutectic bonding
- 5.85 × 5.25 mm² die



SEM cross section image

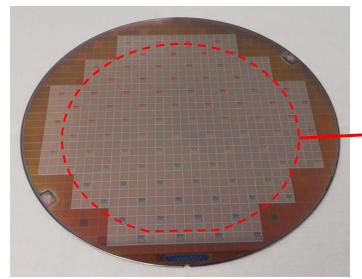
Parent, Samuel, et al. "Single photon avalanche diodes and vertical integration process for a 3D digital SiPM using industrial semiconductor technologies." 2018 IEEE Nuclear Science Symposium and Medical Imaging Conference Proceedings (NSS/MIC). IEEE, 2018.



Wafer level bonding

- Al-Ge eutectic: CMOS aluminum pad to SPAD Ge
- Resizing 200 mm to 150 mm (while matching patterns)

150 mm SPAD wafer

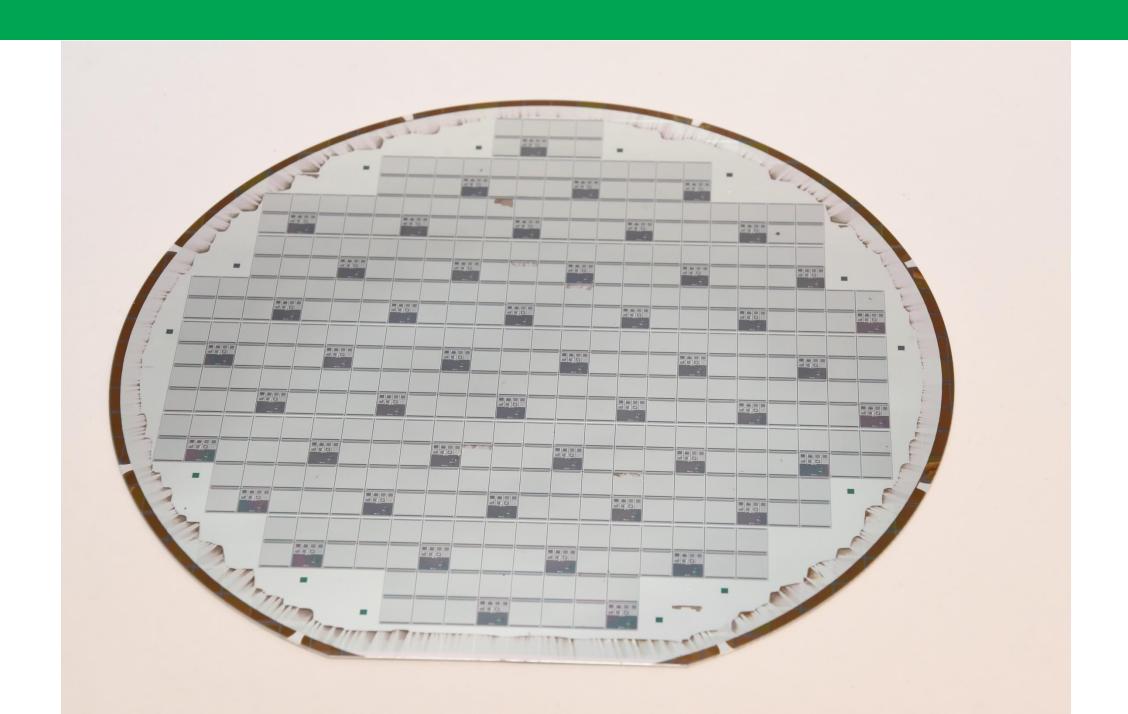


200 mm TSMC 180 nm CMOS wafer



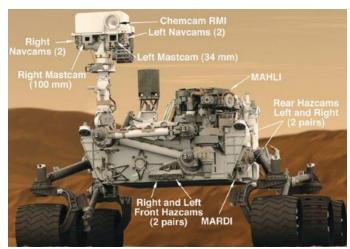
Resized to 150 mm





High-end CCD process line

- --> excellent for SPAD R&D
- 150 mm process line
- low contaminant / gold free clean rooms



The Eyes of the Mars Curiosity Rover. Tech Briefs (2012)



Life on Mars: Rover landing gives boost to Canadian tech sector. The Globe and Mail (2012)

World top 5 MEMS Foundry

- --> excellent for wafer level integration
- 150 mm and 200 mm process line
- Wafer thinning, deep etching, bonding, ...



Courtesy of Teledyne DALSA

MEMS Foundry Rankings (2017 sales in US\$M)	
STMicroelectronics	174
Teledyne DALSA	60
Silex Microsystems	50
TSMC	47
X-Fab	42

Status of the MEMS Industry 2018 Market and technology Report Yole Development (2018)



Teledyne DALSA Semiconductor (est. 1980)

~ 500 employees located at Bromont near Montreal, Canada



PDC designed for low power use in noble liquid experiments

Photon-to-Digital Converter: Architecture

Flag output

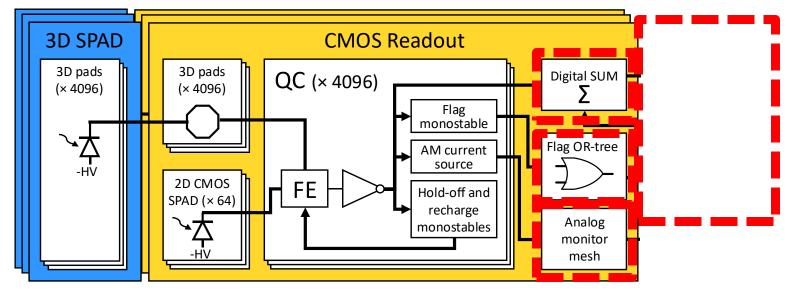
- Pulsed output (adjustable from few ns to tens of ns).
- From an OR-tree.
- Timing jitter better than 100 ps RMS.

Digital Sum

- Digital count of triggered SPADs inside a bin (dynamic range of 4096 photons).
- Adjustable bin width from 10 ns up to μs.
- Internal FIFO of 128 bins.

Analog Monitor

 Current proportional to triggered SPADs.



×64 PDCs/Controller

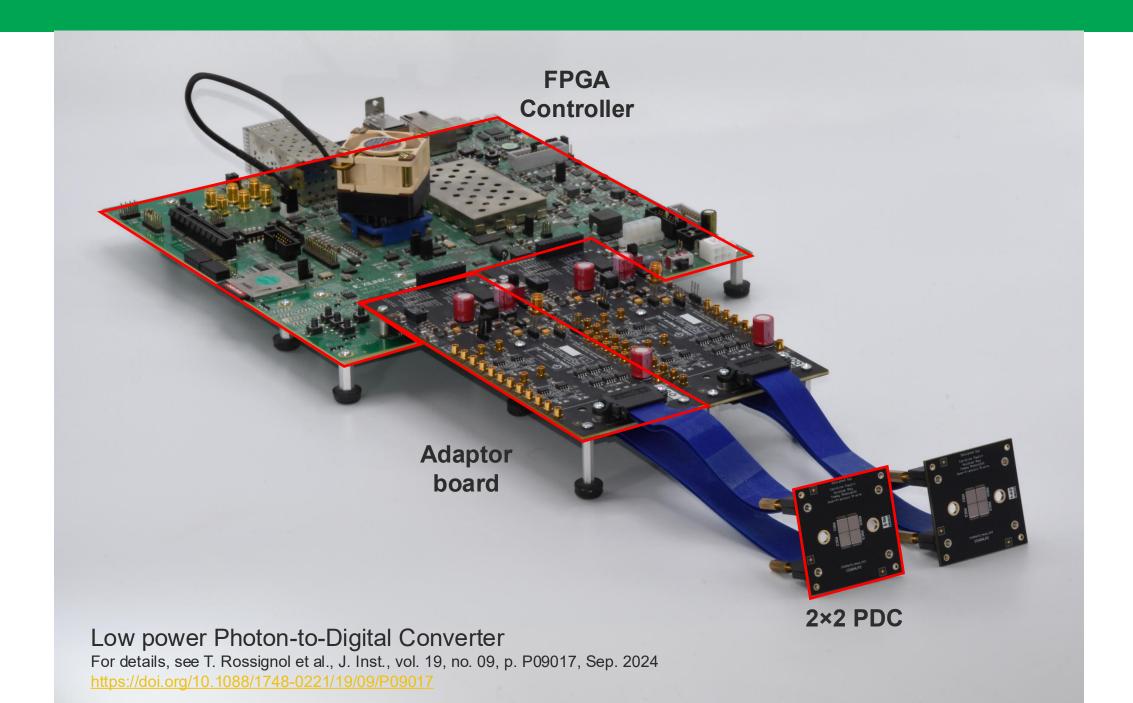
Controller (1 for 64 PDCs)

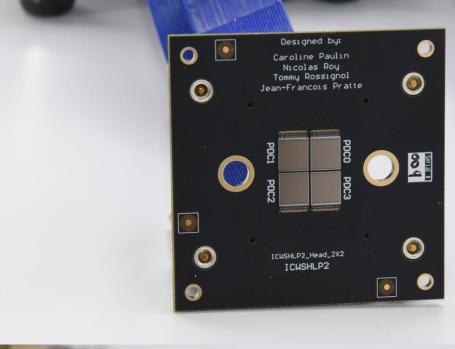
- Start PDC acquisition, based on the number of flag received to discriminate dark count.
- Bank of TDCs for timing measurements on flags.
- Receives data from PDCs and includes postprocessing.
- Communicate with an external computer.

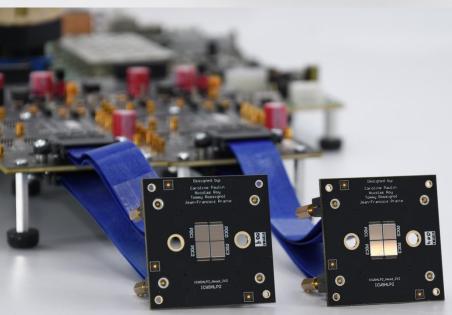


PDC technology dissemination:

Sharing a test platform to allow collaborators to explore the technology









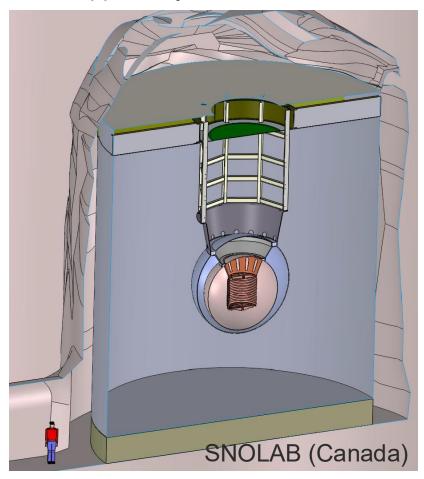


Our global research program:

Photon Detection Modules

nEXO – neutrino search

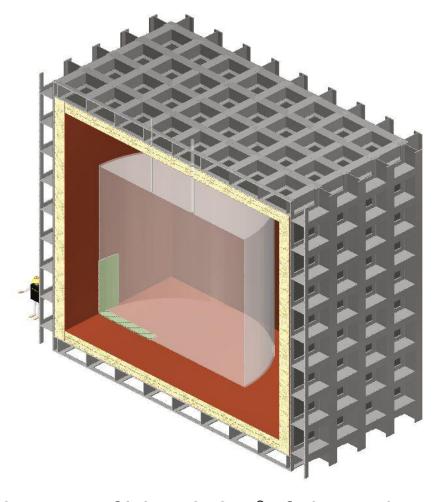
¹³⁶Xe 0νββ decay – xenon as scintillator



5 tonnes of LXe -4.5 m^2 of photon detectors

ARGO – dark matter search

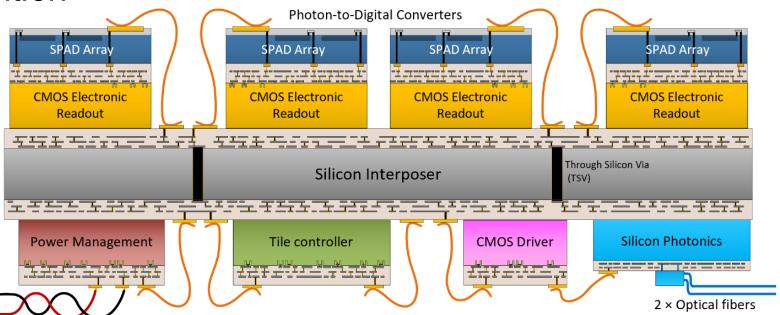
LAr as interaction media and scintillator



300 tonnes of LAr – 250 m² of photon detectors

Photon Detection Module: A Focus on Enabling Large Detection Systems

Our global ambition

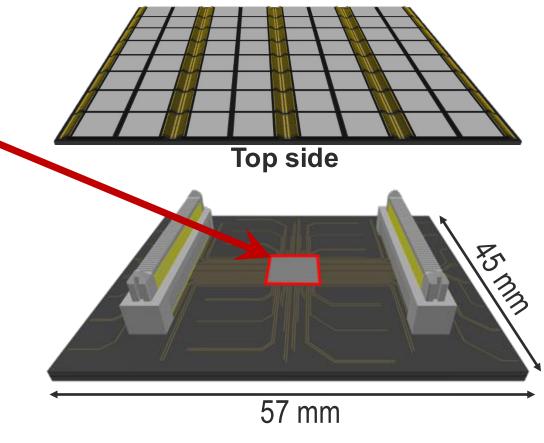


- Demonstrated small tile prototypes
- Silicon interposer for low background large scale integration
- Optical (digital) communication
- Embedded time-to-digital conversion

FPGA-based Controller



ASIC-based Controller

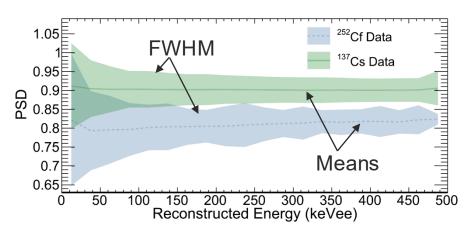






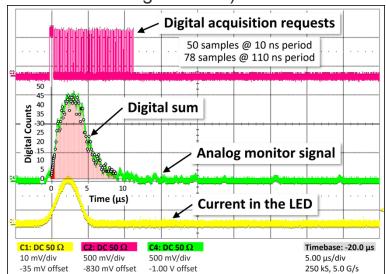


Associate particule neutron imaging – Supported by ORNL



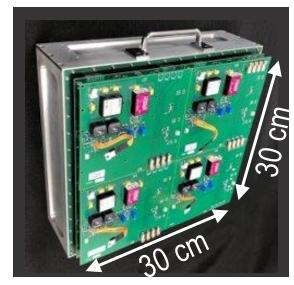
PSD parameter as a function of energy. [1]

Capability of the PDC to measure PSD (here simulated LED light source)

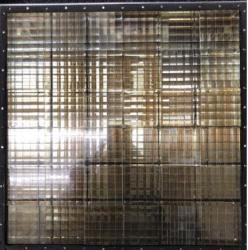


Goal:

next generation of portable neutron detector panel







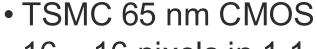
ORNL Portable Pixelated Fast-Neutron Imaging Panel [1] Left: Multi-Anode PMT | Right: Pixelated scintillators



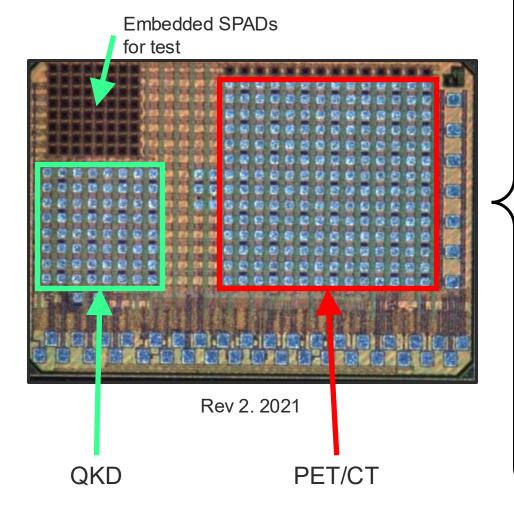
Photo-to-Digital Converteur designed for precise timing applications

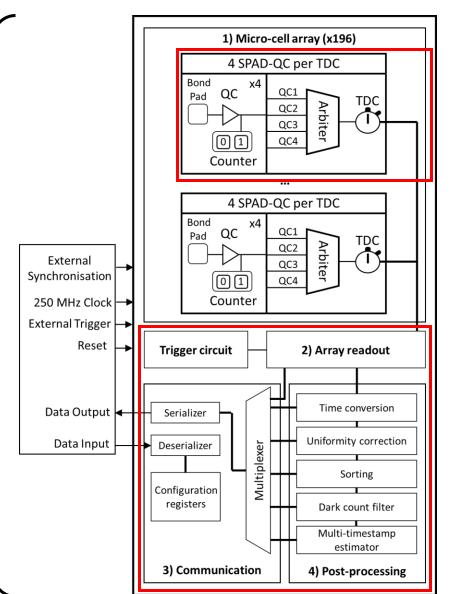
Quantum key distribution,
Wavefront sensing,
Medical imaging ToF-PET, ToF-CT,

. . .



• 16 \times 16 pixels in 1.1 \times 1.1 mm²





1 Sub-20 ps TDC for 4 SPADs

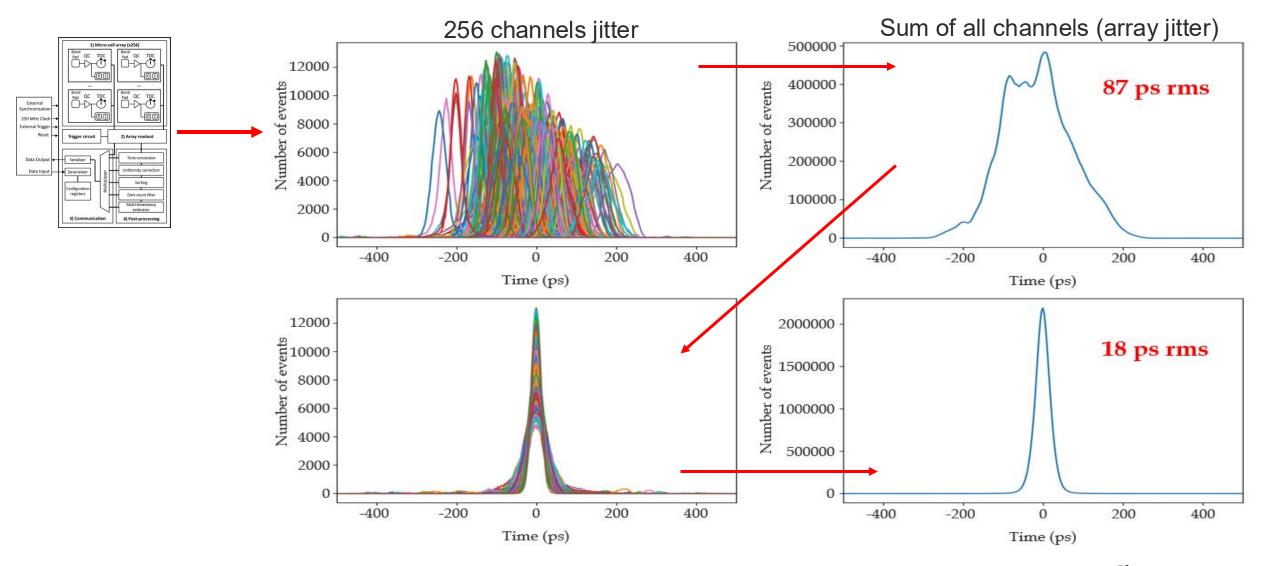
Advanced digital signal processing:

- Time windowing
- TDC code to time conversion
- Uniformity correction
- Timestamp sorting
- Dark count filtering
- BLUE

And for QKD

Time categorization

Embedded Digital Signal Processing Example: Uniformity Correction





ToF Computed Tomography

Using time-of-flight to exclude noise from scattering X-ray photons

ToF Scatter Rejection Principle

Detector array

Time-correlated

How do that?

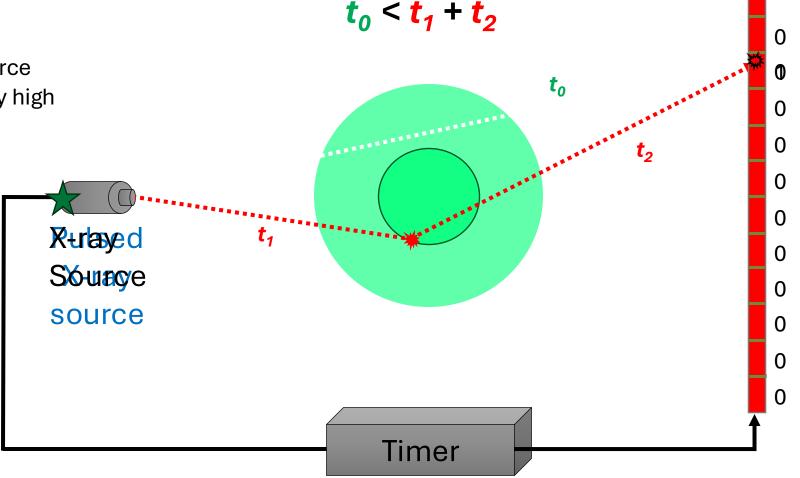
To do this we need:

- Synchronized pulsed X-ray source
- Time-resolved detectors of very high precision (~10-200 ps FWHM)

Threshold for rejection:

t_{th}~10-500 ps FWHM

$$t_1 + t_2 > t_0 + t_{th}$$





Quantum Key Distribution

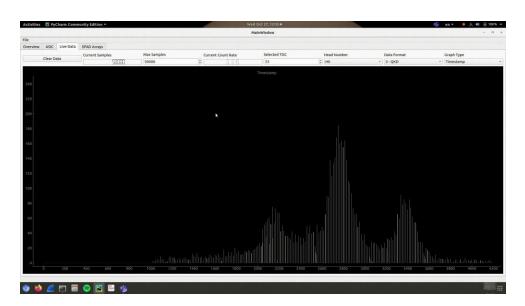
Exploiting in timestamp processing

Raw time stamp data

Each photon is timestamped in the chip

- ~20ps resolution and precision
- Timestamps are transmitted to the computer

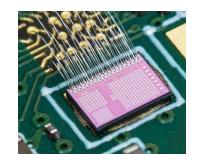
The histogram shows 3 modes to the distribution corresponding to the projection of the 4 states of the qubit onto the time base (center bin holds 2 states)



Classified time-bins

Timestamps are classified inside the chip into 5 bins

- Two bins for out-of-range values
- Programmable bins



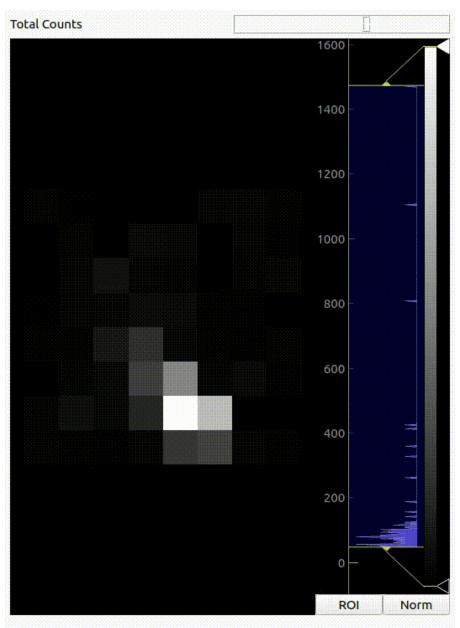
This provides effective data compression, limiting the relevant information to only 2-3 bits for each qubit



Tracking

UDS

- Applied in an array we get
 - The timestamps or time bins
 AND
 - Photon location on the array



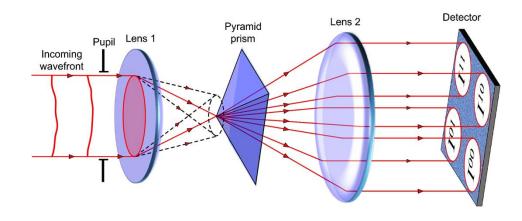
serge.charlebois@usherbrooke.ca



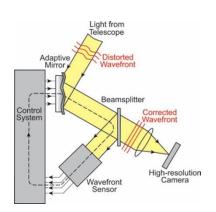
Rapid Wavefront Sensing

For exoplanet search

Pyramidal Wavefront Sensing for AO



Shatokhina et al. 2020 <u>10.1117/1.JATIS.6.1.010901</u>

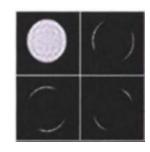


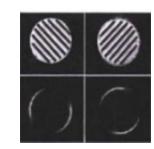
Conventional Pyramid WaveFront Sensing (PWFS)

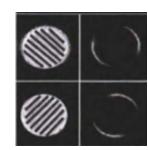
- Integrates photons over a modulation cycle

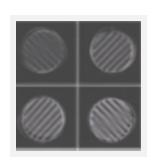
Time-resolved PWFS

- Separates a modulation cycle into 48 frames
- Because each frame captures one diffraction pattern
 - Increases signal to noise ratio









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Conclusion

3D Photon-to-Digital Converters in fabrication

- PDC fabrication runs planned every 4-6 months
 - Increasing the manufacturability,
 - Tuning/exploring performance improvements
- PDC now being assembled on test boards (instead using probing station)



- Training on CMOS-only boards
- PDC boards should be available Fall 2025.



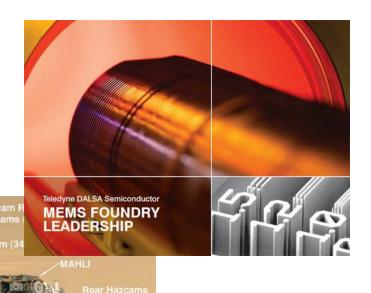
High performance Photon-to-Digital Converter

- Small array demonstrated: quenching σ <5 ps, TDC σ <10 ps
- Completing design/validation of 5×5 mm² array → 2026
 - Readout prototyping → 2026
- Wafer level 3D assembly with SPADs → 2027











On PDC development

- T. Rossignol et al., "A 3D photon-to-digital converter readout for low-power and large-area applications," J. Inst., vol. 19, no. 09, p. P09017, Sep. 2024, doi: 10.1088/1748-0221/19/09/P09017.
- S. Parent et al., "Wafer-Level Characterization and Monitoring Platform for Single-Photon Avalanche Diodes," IEEE J. Electron Devices Soc., vol. 12, pp. 127–137, 2024, doi: 10.1109/JEDS.2024.3359088.
- J.-F. Pratte et al., "Fast neutron radiography-based on single-photon digital photosensor: concept and demonstration," in Hard X-Ray, Gamma-Ray, and Neutron Detector Physics XXV, N. J. Cherepy, M. Fiederle, and R. B. James, Eds., San Diego, United States: SPIE, Oct. 2023, p. 12. doi: 10.1117/12.2682610.
- F. Nolet et al., "Quenching Circuit Discriminator Architecture Impact on a Sub-10 ps FWHM Single-Photon Timing Resolution SPAD," Instruments, vol. 7, no. 2, p. 16, Apr. 2023, doi: 10.3390/instruments7020016.
- S. Carrier et al., "Towards a Multi-Pixel Photon-to-Digital Converter for Time-Bin Quantum Key Distribution," Sensors, vol. 23, no. 7, p. 3376, Mar. 2023, doi: 10.3390/s23073376.
- Rossignol, T. "Conception d'un circuit de lecture d'une matrice de photodiodes à avalanche monophotonique pour les détecteurs de physique des particules dans les gaz nobles liquéfiés". Dissertation, Université de Sherbrooke, 2020.

On ToF CT

- D. Gaudreault, J. Rossignol, Y. Bérube-Lauzière, and R. Fontaine (2021), IEEE Transactions on Radiation and Plasma Medical Sciences, vol. 5, no. 3, pp. 343–349
- J. Rossignol, G. Bélanger, D. Gaudreault, A. C. Therrien, Y. Bérubé-Lauziére, et R. Fontaine, « Time-of-flight scatter rejection in x-ray radiography », Phys. Med. Biol., vol. 69, no 5, p. 055027, mars 2024, doi: 10.1088/1361-6560/ad1f85.
- J. Rossignol, G. Bélanger, M. Fromont, A. C Therrien, R. Fontaine, et Y. Bérubé-Lauzière, « Scatter estimation and correction using time-of-flight and deconvolution in x-ray medical imaging », Phys. Med. Biol., vol. 69, no 17, p. 175017, sept. 2024, doi: 10.1088/1361-6560/ad700e.
- G. Belanger, J.Rossignol, , Y. Berube-Lauziere, and R. Fontaine (2024), To be published

References and links

On ToF PET

- Pratte, J.-F., et al. "3D Photon-to-Digital Converter for Radiation Instrumentation: Motivation and Future Works" (2021) Sensors;21(2):598. doi: 10.3390/s21020598
- Parent, S., et al. "Single photon avalanche diodes and vertical integration process for a 3D digital SiPM using industrial semiconductor technologies." 2018 IEEE Nuclear Science Symposium and Medical Imaging Conference Proceedings (NSS/MIC). IEEE, 2018.
- Parent, S., et al. "Characterization and Monitoring Platform for Single-Photon Avalanche Diodes in the Development of a Photon-to-Digital Converter Technology.", 2022 IEEE International Conference on Microelectronic Test Structures Proceedings (ICMTS). IEEE, 2022.
- Parent, S., "Design of a Vertically Integrated Single-Photon Avalanche Diodes, Manufactured at Wafer level, for a Photon-to-Digital Converter Technology", PhD Thesis (to be published), 2022.
- Nolet, F. et al., "Quenching Circuit and SPAD Integrated in CMOS 65 nm with 7.8 ps FWHM Single Photon Timing Resolution", Instruments 2018, 2, 19.
- Nolet, F. et al., "Digital SiPM channel integrated in CMOS 65 nm with 17.5 ps FWHM single photon timing resolution", Nuclear Instruments and Methods in Physics Research Section A, 912, 29-32, 2018.
- Nolet, F. et al., "A 256 Pixelated SPAD readout ASIC with in-Pixel TDC and embedded digital signal processing for uniformity and skew correction", Nuclear Instruments and Methods in Physics Research Section A, 949, 162891, 2020.
- Lemaire, W. et al., "Embedded time of arrival estimation for digital silicon photomultipliers with in-pixel TDCs", Nuclear Instruments and Methods in Physics Research Section A, 959, 163538, 2020.
- Roy, N., et al. "Low Power and Small Area, 6.9 ps RMS Time-to-Digital Converter for 3-D Digital SiPM", IEEE Transactions on Radiation and Plasma Medical Sciences, 1(6) 2017.
- Therrien, A. C., et al. "Energy discrimination for positron emission thomography using the time information of the first detected photons", Journal of Instrumentation, 13, 2018.
- Loignon-Houle, F., et al., "DOI estimation through signal arrival time distribution: a theoretical description including proof of concept measurements", Physics in Medicine and Biology, 66(9), pp. 095015, 2021.

EXtras



First PDC Characterization Results

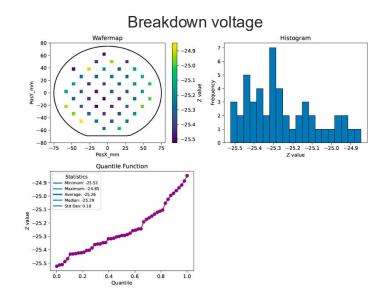
Process control monitor – SPAD basic and other characteristics

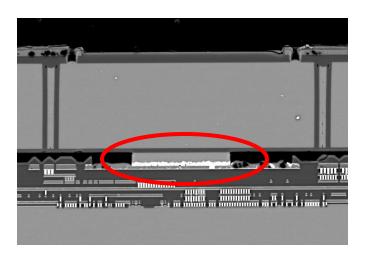
Completion of the first 3 wafers of PDC

- 1st run: Delivered on Oct. 13th 2024 (3 wafers)
- 2nd run: Delivered on April 29th 2025 (2 wafers)

Process control monitor results:

- Standard foundry process monitoring structures
 - All in specs on all wafers (~30 types of tests)
- SPAD performances: comparable to our previous SPAD runs
 - Breakdown voltage on specifications: 25.26V ± 0.18Vσ (@ 1µA bias)
 - DCR ~ 50-60 cps/SPAD @ 20-25% V_{ex} @ RT \rightarrow ~0.03 cps/µm²
 - Afterpulsing ~1.3%
- SPAD-to-Quench connection yield > 99.8%
 - Only 30 defective structures out of 980 (47040 contacts)

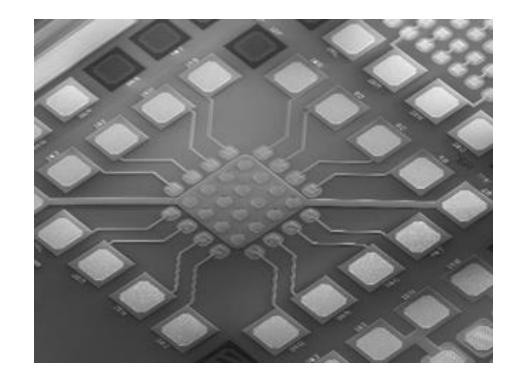




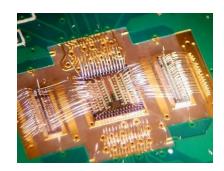
SPADs with external quenching

- Testing individual SPADs of a small array
 - SPADs with trenches, nominally identical to those in PDCs
 - Anode routed to top surface (resistive vias)

- Crosstalk ongoing
 - Enabling one or two SPADs and comparing count rate
 - Preliminary: ~10%
 - To come: study through time delay distributions

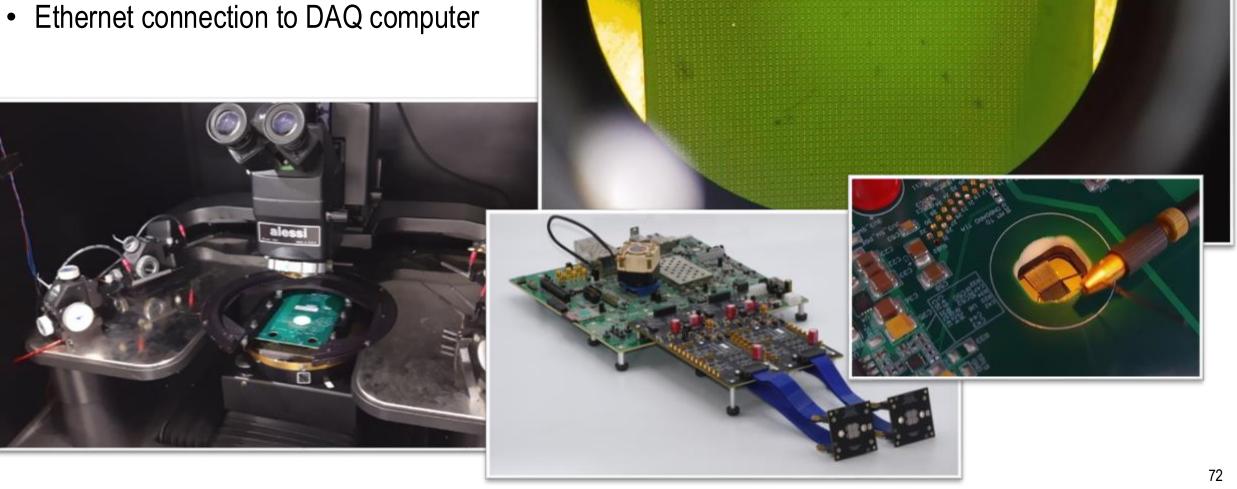


- SPTR measurement ongoing
 - External quenching slows response and increases SPTR
 - Preliminary: 70 to 150 ps (wavelength dependant), comparable to 2023 results
 - To come: measurements on the PDC itself with local quenching



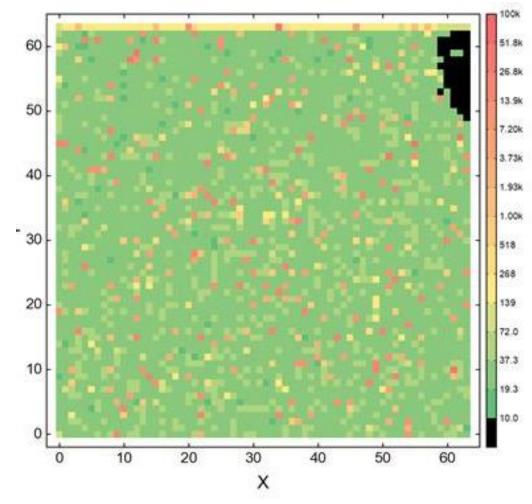
 Active testing of PDC performed with FPGA controller board*

Flat cable connecting a probe card



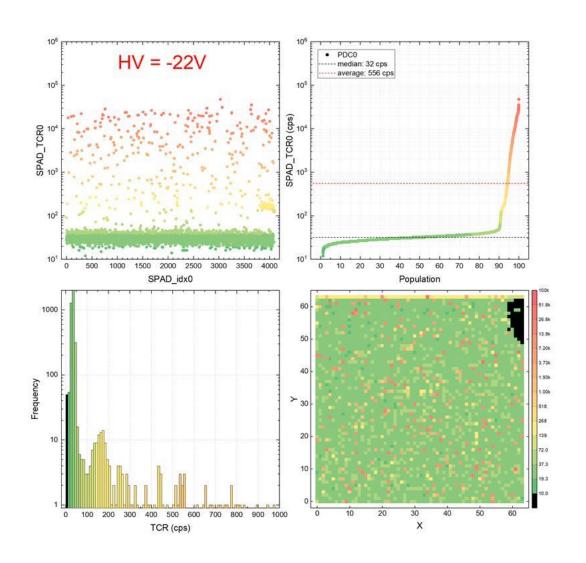
- Scan of all 4096 SPADs of the PDC
 - Activate a single SPAD
 - Therefore no crosstalk contribution in this measurement
 - Count "events" over one second → TCR
 - In this map: using flag output and counter in FPGA
 - Also possible: use the numeric sum (to come)

Map of total count rate (DCR+AP) per SPAD (4096)

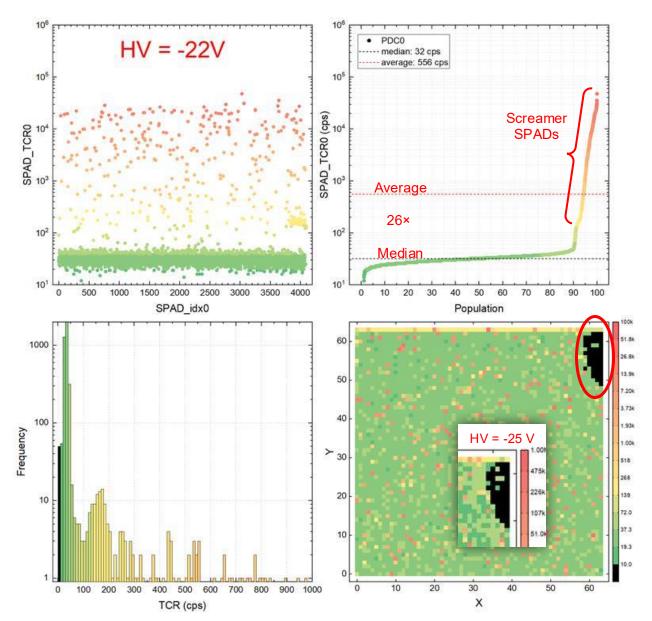


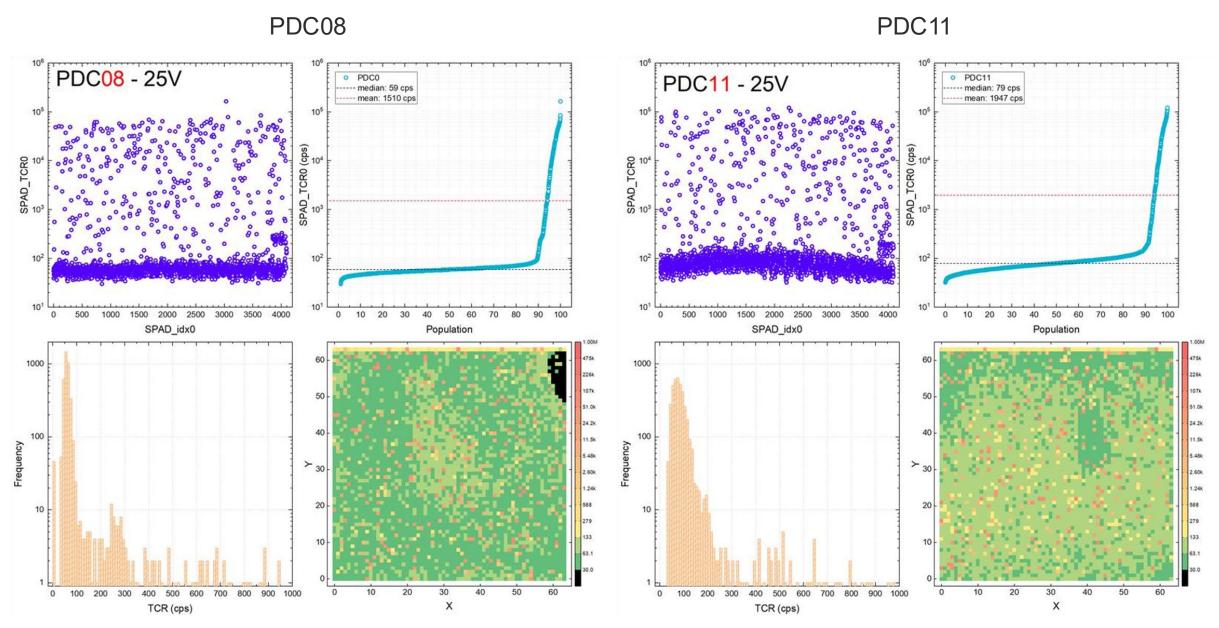
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 - In this map: using flag output and counter in FPGA
 - Also possible: use the numeric sum (to come)
- Upper left: SPAD index mapping
- Upper right: Population ordered by TCR
 - Allow identifying the "screamer" sub-population and its impact on overall TCR
- Bottom left: TCR histogram

Four ways to look at the data to get a PDC's "unique" fingerprint



- 4096 SPADs in a 64 × 64 array
- 46 SPADs not responding (at -22 V bias)
 - 4 of these SPADs respond at -25 V bias
 - Under investigation
- Average TCR is dominated by screamers
 - 5% to 7% of population (depends on definition)
 - Median TCR is 26× lower than average TCR
 - Typical from literature, also expected in SiPMs



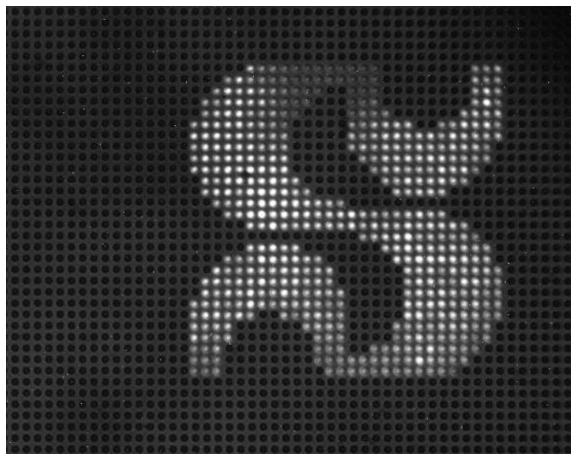


PDC Characterization – Light emission

- During avalanche, SPADs emit light
 - Source of cross-talk both internal and external

- Demonstration of the capability of single SPAD activation/deactivation
 - SPADs forming a motif were activated
 - Long exposure of a sensitive camera reveals electroluminescence of the activated SPADs (here deliberately saturated to the show!)
 - Deactivated SPADs show no emission.

 We will investigate the use of light emission to rapidly characterize PDC DCR



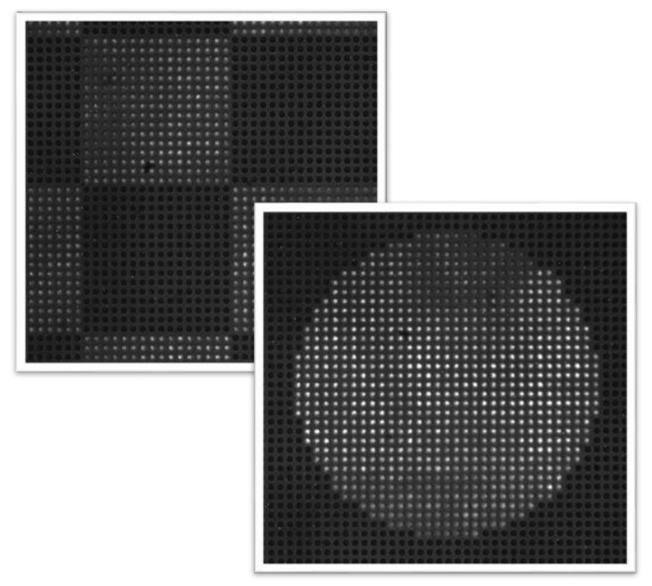
Light emission – PDC11 – 2 min exposure 24.5 V

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